

7 onto said substrate and having two conductive pads or other conductive terminal
8 areas where electrical connection to said antenna [~~may be~~] is capable of being
9 made;

10 an RFID tag or smart card transceiver integrated circuit integrated on said
11 substrate so as to have RF input/output terminals which are electrically coupled to
12 said terminal areas of said antenna.

1 2. (Amended) An integrated circuit structure comprising:

2 a plastic substrate;

3 a layer of silicon dioxide or silicon nitride having a thickness such that little
4 or no differential strain between the substrate and said layer occurs at any
5 temperature in the normal operating temperature range of said integrated circuit;

6 an RFID tag or smart card transceiver integrated circuit integrated on said
7 substrate on top of said layer of silicon dioxide or silicon nitride so as to have RF
8 input/output terminals, and having a layer of insulating material formed over said
9 integrated circuit;

10 an antenna conductor which is bonded onto, integrated onto or printed
11 onto said insulating layer covering said integrated circuit so as to make electrical
12 connection with said RF input/output terminals.

1 3. (Amended) An integrated circuit structure comprising:

2 a first plastic or glass or plastic laminated to glass substrate;

3 a layer of silicon dioxide or silicon nitride having a thickness such that little
4 or no differential strain between the substrate and said layer occurs at any
5 temperature in the normal operating temperature range of said integrated circuit;

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CONT.

6 an antenna conductor which is bonded onto, integrated onto or printed
7 onto said substrate and having two conductive pads or other conductive terminal
8 areas where electrical connection to said antenna ~~[may be]~~ is capable of being
9 made;

10 an RFID tag or smart card transceiver integrated circuit integrated ~~[as one~~
11 ~~of a very large number of said integrated circuits]~~ on a ~~[large]~~ second plastic or
12 glass substrate using flat panel display manufacturing equipment, said integrated
13 circuit being cut from said second plastic or glass substrate and bonded or
14 ~~[otherwise]~~ otherwise attached to said first plastic substrate and having RF
15 input/output terminals; and

16 wires connected ~~[in any way]~~ between said RF input/output terminals of
17 said integrated circuit and said terminal areas of said antenna.

REMARKS

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19 The Examiner objected to claim 3 because of a spelling error. This error has been
20 corrected.

21 With regard to the rejection of claims 1-3 for indefiniteness of the limitation "little
22 differential strain between the substrate", the Examiner has slightly misquoted the
23 limitation in question. Nevertheless, the following passage from the Summary of the
24 Invention defines what is meant by the quoted limitation in the passage which is used to
25 define an acceptable amount of strain:

26 As used in the claims, the phrase "little or no differential strain between the
27 substrate and said layer occurs in the normal operating temperature range of said
28 integrated circuit" means not enough difference in the strain between the strain in
29 the substrate at a given temperature and the layer of oxide, nitride or other
30 material coated over the substrate occurs to cause fractures or stress that